PCN Number:			201	706150	001		PCN Date:	Ju	June 27, 2017			
Tit	le:	Datasheet fo	r LMR	23610-	-Q1							
Cus	stome	r Contact:	PCN /	Aanage r					Dej	ot:	Quality Services	
Cha	ange 1	Гуре:										
	Assei	nbly Site				Design		[Wafer	Bump Site	
Assembly Process			\boxtimes	Data Sheet				Wafer	Bump Material			
Assembly Materials				Part number change				Wafer Bump Process				
Mechanical Specification				Test Site					Fab Site			
Packing/Shipping/L			'Labeli	Labeling		Test Process					Fab Materials	
										Wafer Fab Process		
Notification Details												
Description of Change: Texas Instruments Incorporated is announcing an information only notification.												
The product datasheet(s) is being updated as summarized below. The following change history provides further details.												
INSTRUMENTS ENVSAR4A - DECEMBER 2016 - REVISED APRIL 2017												
Changes from Original (December 2016) to Revision A Page												
Changed the value for HBM from ±2500 to ±2000												
Device Family				e enan	9		Change From:			hange ⁻	To:	
LMR23610-Q1				SNVSAR4			SNVSAR4A					
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/LMR23610-Q1												
Reason for Change:												
To accurately reflect device characteristics.												
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):												
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.												
Changes to product identification resulting from this PCN:												
None.												
Pro	Product Affected:											
		L0AQDDAQ1	LMI	R23610	DAQ	DDARQ1						
							1					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com